





P-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

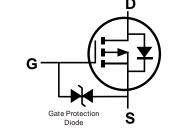
Mechanical Data

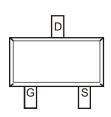
- Case: SOT523
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Terminal Connections: See Diagram
- Weight: 0.002 grams (Approximate)





SOT523





Top View

Equivalent Circuit

Top View

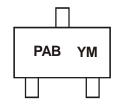
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2004TK-7	SOT523	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 Halogen- and Antimony-free "Green" products are defined as those which contain < 000ppm browing < 000ppm chloring (<1500ppm total Rr. + Cl) and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- $4. \ For \ packaging \ details, \ go \ to \ our \ website \ at \ https://www.diodes.com/design/support/packaging/diodes-packaging/.$

Marking Information



PAB = Product Type Marking Code YM = Date Code Marking Y = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	2006	2007		2014	2015	2016	2017	2018	2019	2020	2021	2022
Code	Т	U		В	С	D	Е	F	G	Н	I	J
Month	Jan	Feb	Mar	Apr	Mav	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Chara	acteristic		Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±8	V
Drain Current (Note 5)	Steady State	$T_A = +25$ °C $T_A = +85$ °C	I _D	-430 -310	mA
Pulsed Drain Current (Note 6)			I _{DM}	-750	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	230	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	558	°C/W
Total Power Dissipation (Note 6)		P_{D}	320	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{θJA}	393	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

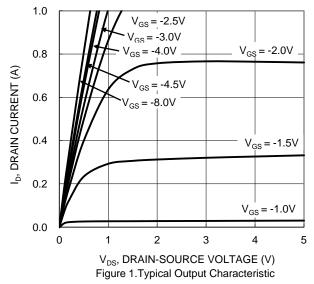
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition			
OFF CHARACTERISTICS (Note 7)									
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_		V	$V_{GS} = 0V, I_D = -250\mu A$			
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1.0	μΑ	V _{DS} = -20V, V _{GS} = 0V			
Gate-Source Leakage	I _{GSS}	_	_	±1.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$			
ON CHARACTERISTICS (Note 7)									
Gate Threshold Voltage	V _{GS(TH)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$			
			0.7	1.1		$V_{GS} = -4.5V$, $I_D = -430mA$			
Static Drain-Source On-Resistance	R _{DS(ON)}	_	1.0	1.6	Ω	$V_{GS} = -2.5V$, $I_D = -300$ mA			
			1.3	2.4		$V_{GS} = -1.8V, I_D = -150mA$			
Diode Forward Voltage	V_{SD}	_	-0.8	-1.4	V	$V_{GS} = 0V, I_{S} = -115mA$			
DYNAMIC CHARACTERISTICS (Note 8)									
Input Capacitance	C _{iss}	_	47		pF	10)/)/ 0)/			
Output Capacitance	Coss		6.8	_	pF	$V_{DS} = -16V, V_{GS} = 0V$ -f = 1.0MHz			
Reverse Transfer Capacitance	C _{rss}	1	4.9	_	pF	1 = 1:0WI 12			
Gate Resistance	R_{g}		240	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$			
Total Gate Charge V _{GS} = -4.5V	Q_{g}	1	0.55	_	nC				
Total Gate Charge V _{GS} = -8V	Qg	1	0.97	_	nC	$V_{DS} = -10V, I_{D} = -250mA$			
Gate-Source Charge	Q_{gs}		0.05	_	nC				
Gate-Drain Charge	Q_{gd}	_	0.1	_	nC				
Turn-On Delay Time	t _{D(ON)}	_	5.9	_	ns				
Turn-On Rise Time	t _R	_	3.3	_	ns	$V_{DD} = -3V, V_{GS} = -2.5V,$			
Turn-Off Delay Time	t _{D(OFF)}	_	25.5	_	ns	$R_G = 25\Omega$, $I_D = -100 \text{mA}$			
Turn-Off Fall Time	t _F	_	19.3	_	ns				
Reverse Recovery Time	t _{RR}		7.3	_	ns	I _F =-1A, di/dt=-100A/μs			
Reverse Recovery Charge	Q_{RR}		1.9	_	nC	I _F =-1A, di/dt=-100A/μs			

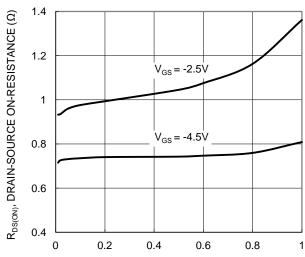
5. Device mounted on FR-4 PCB, with minimum recommended pad layout.

^{6.} Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.

^{7.} Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.







I_D, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

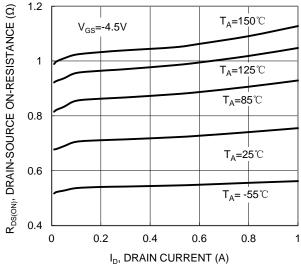


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

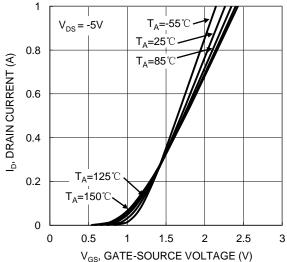
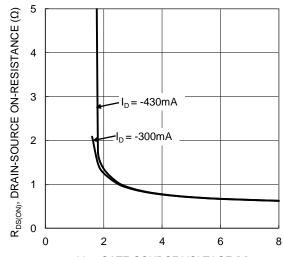
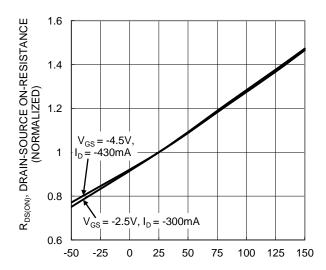


Figure 2. Typical Transfer Characteristic



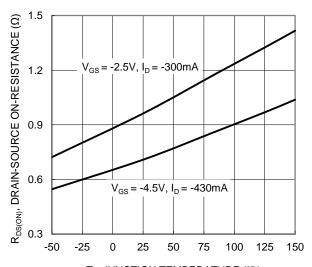
V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic



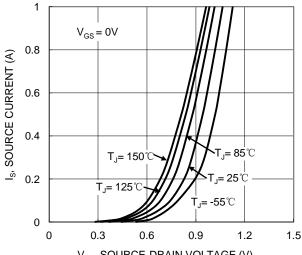
T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Temperature







T_J, JUNCTION TEMPERATURE (°C) Figure 7. On-Resistance Variation with Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

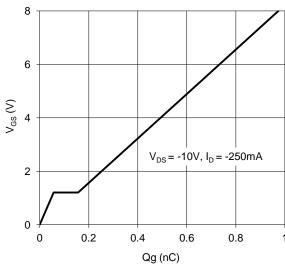
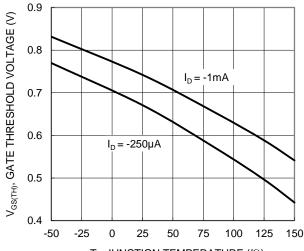
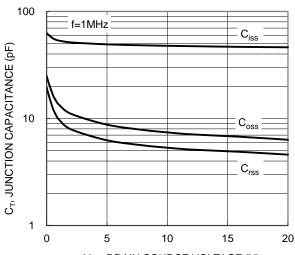


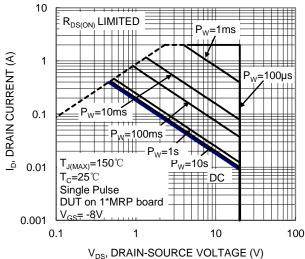
Figure 11. Gate Charge



 T_J , JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. JunctionTemperature



V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 10. Typical Junction Capacitance



V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



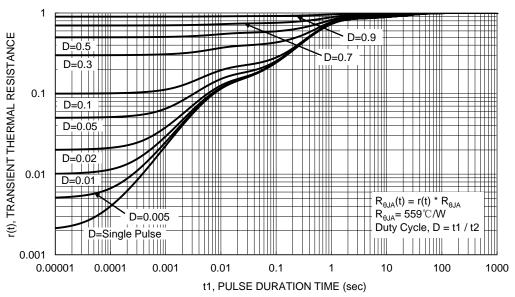
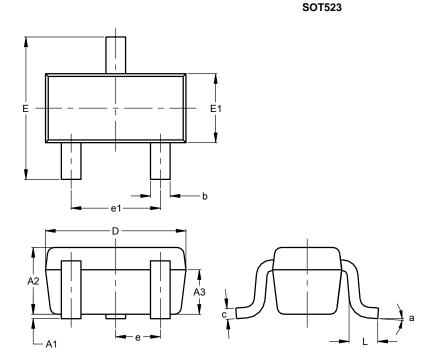


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



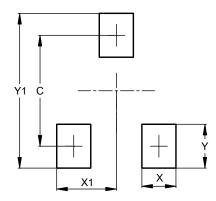
SOT523						
Dim	Min	Max	Тур			
A1	0.00	0.10	0.05			
A2	0.60	0.80	0.75			
A3	0.45	0.65	0.50			
b	0.15	0.30	0.22			
С	0.10	0.20	0.12			
D	1.50	1.70	1.60			
Е	1.45	1.75	1.60			
E1	0.75	0.85	0.80			
е	0.50 BSC					
e1	0.90	1.10	1.00			
L	0.20	0.40	0.33			
а	0°		8°			
All Dimensions in mm						



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT523



Dimensions	Value (in mm)		
С	1.29		
Х	0.40		
X1	0.70		
Υ	0.51		
Y1	1.80		

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